

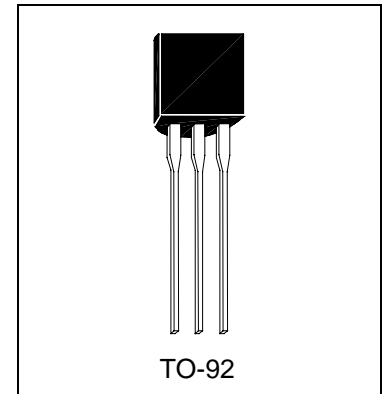


# HSB772S

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HSB772S is designed for using in output stage of 0.75W amplifier, voltage regulator, DC-DC converter and driver.



## Absolute Maximum Ratings

- Maximum Temperatures
  - Storage Temperature ..... -55 to +150 °C
  - Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (Ta=25°C) ..... 750 mW
- Maximum Voltages and Currents (Ta=25°C)
  - VCBO Collector to Base Voltage ..... -40 V
  - VCEO Collector to Emitter Voltage..... -30 V
  - VEBO Emitter to Base Voltage ..... -5 V
  - IC Collector Current ..... -3 A

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA, IE=0
BVCEO	-30	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-30V, IE=0
IEBO	-	-	-1	uA	VEB=-3V, IC=0
*VCE(sat)	-	-0.3	-0.5	V	IC=-2A, IB=-0.2A
*VBE(sat)	-	-1	-2	V	IC=-2A, IB=-0.2A
*hFE1	30	-	-		VCE=-2V, IC=-20mA
*hFE2	100	160	400		VCE=-2V, IC=-1A
fT	-	80	-	MHz	VCE=-5V, IC=-0.1A, f=100MHz
Cob	-	55	-	pF	VCB=-10V, f=1MHz

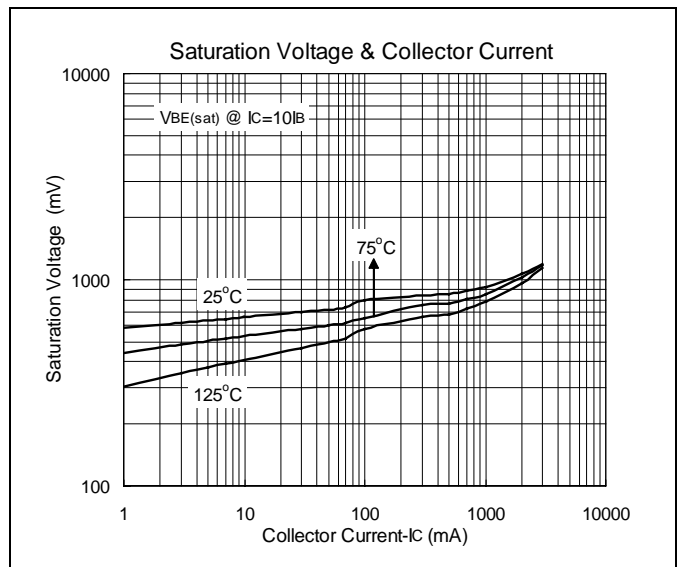
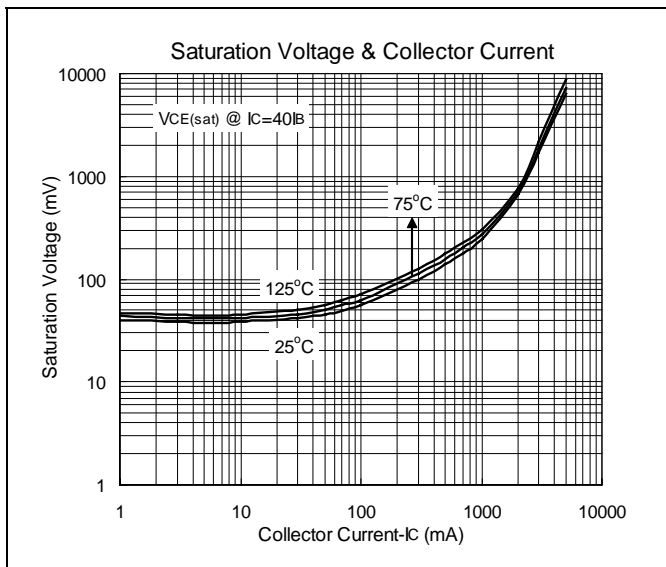
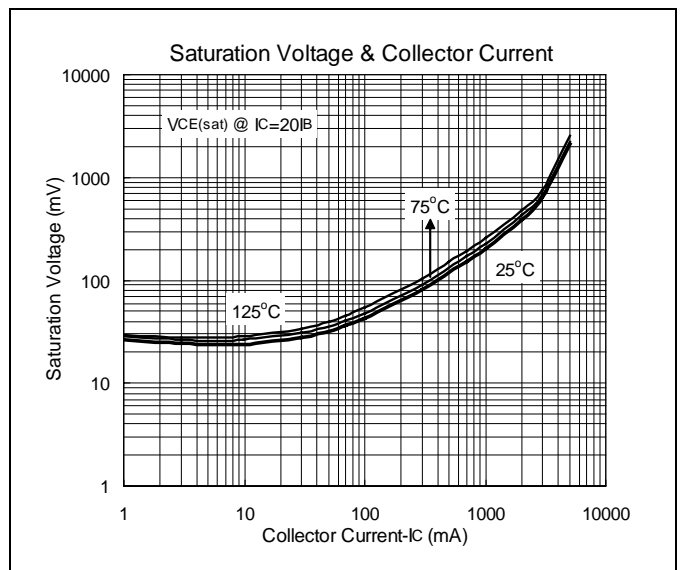
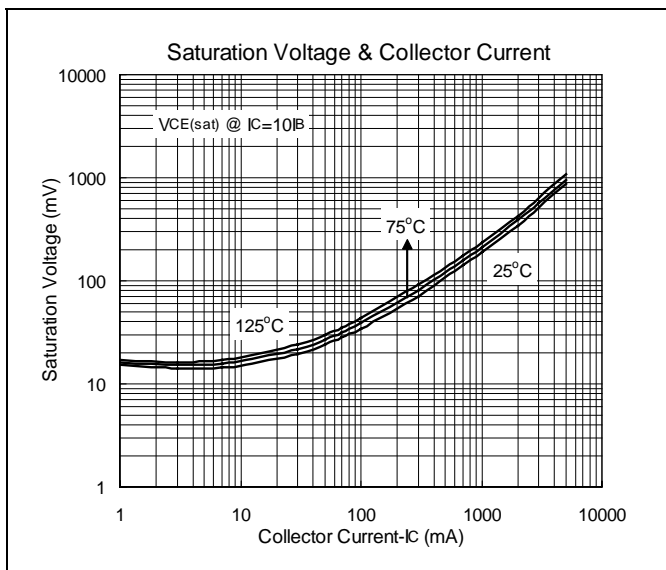
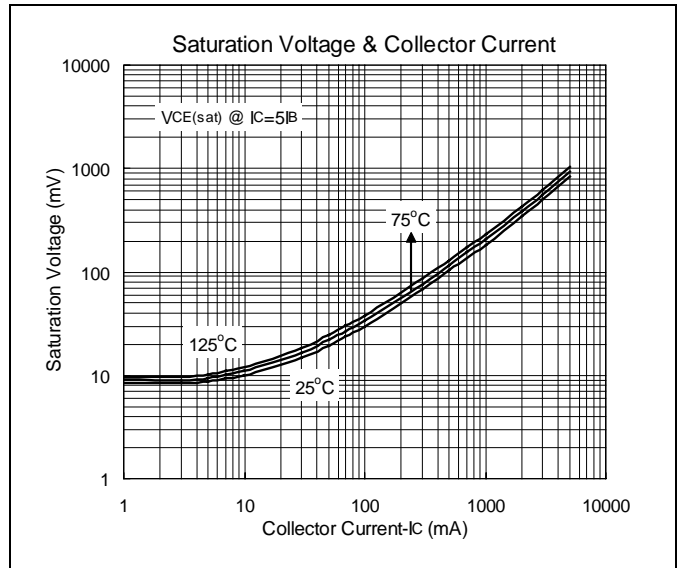
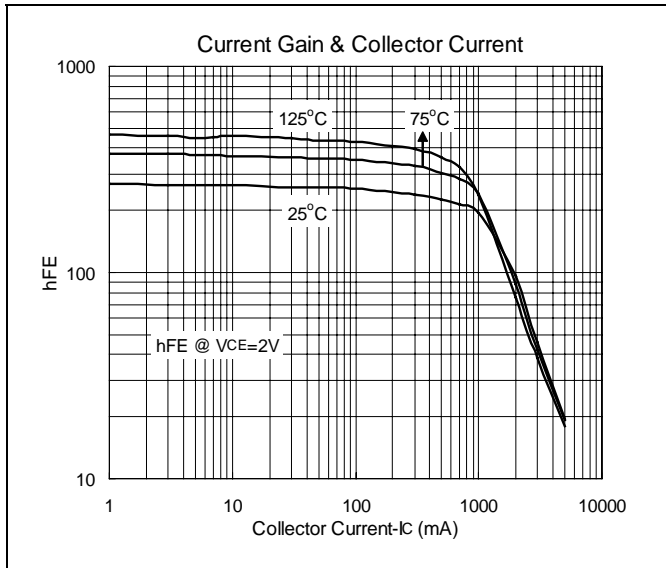
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

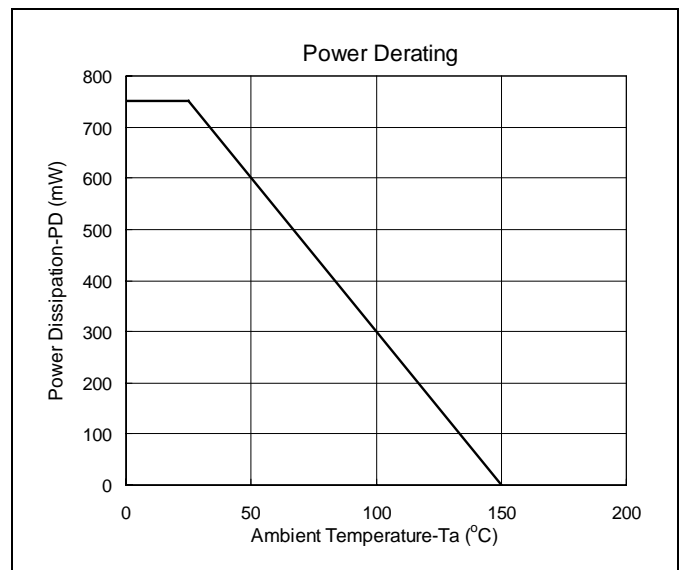
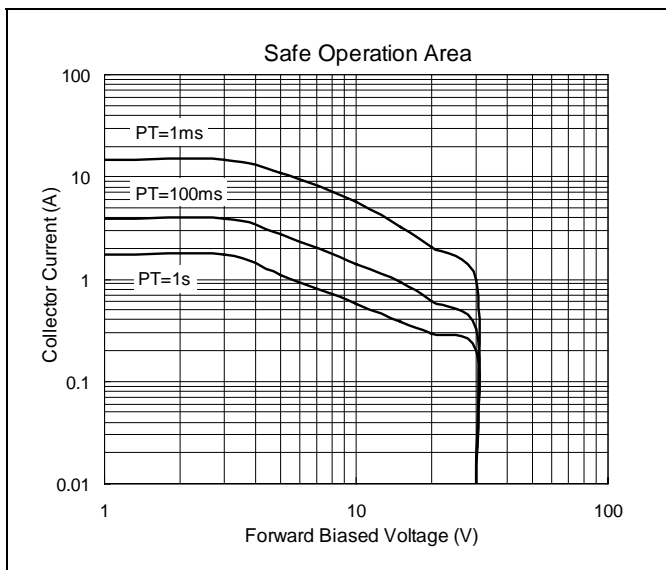
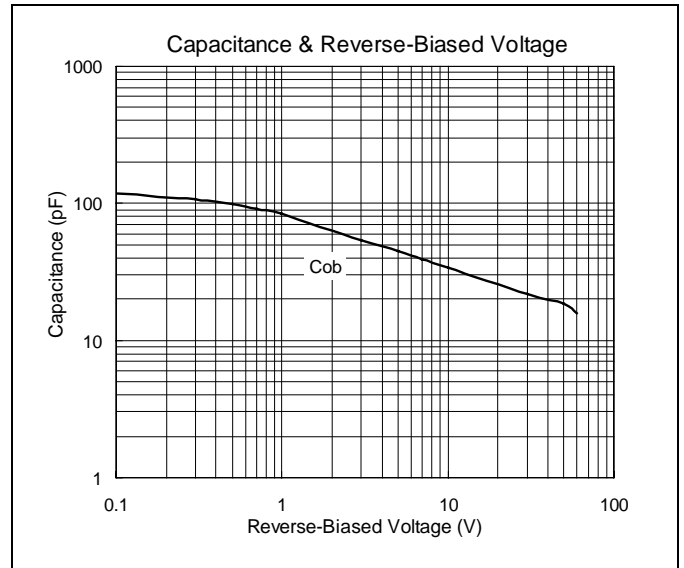
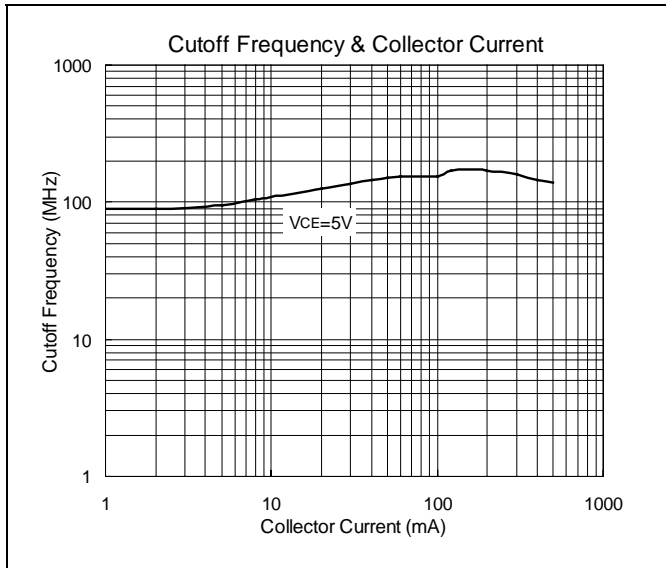
## Classification Of hFE2

Rank	Q	P	E
Range	100-200	160-320	200-400



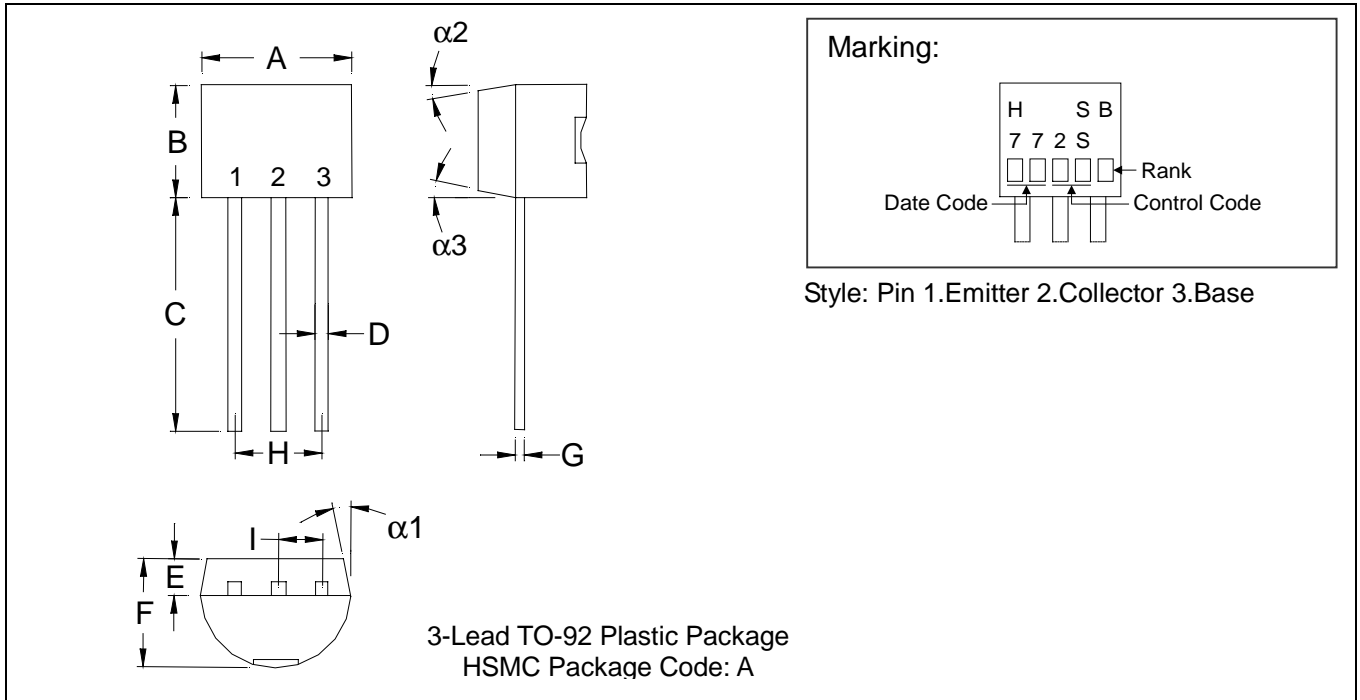
### Characteristics Curve







### TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes: 1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.  
 2. Controlling dimension: millimeters.  
 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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